

P-Channel 12 V (D-S) MOSFET

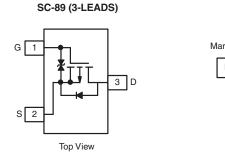
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A)	Q _g (Typ.)		
	0.640 at V _{GS} = - 4.5 V	- 0.48			
	0.880 at V _{GS} = - 2.5 V	- 0.41			
- 12	1.200 at V _{GS} = - 1.8 V	- 0.35	1.15 nC		
	1.443 at V _{GS} = - 1.5 V	- 0.10			
	2.475 at V _{GS} = - 1.2 V	- 0.05			

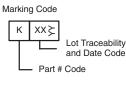
FEATURES

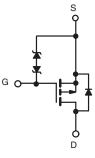
- TrenchFET[®] Power MOSFET
- Typical ESD protection: 700 V (HBM)
- Fast Switching Speed
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Portable Devices such as Smart Phones, Tablet PCs and Mobile Computing
 - Load Switch for Low Voltage Gate Drive
 - Load Switch for 1.2 V Power Line







Ordering Information: Si1011X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 12	v	
Gate-Source Voltage		V _{GS}	± 5	v	
Continuous Drain Current (T _{.1} = 150 °C)	T _A = 25 °C		- 0.48 ^{b, c}		
Continuous Drain Current $(T_j = 150^{\circ} C)$	T _A = 70 °C	I _D	- 0.38 ^{b, c}	A	
Pulsed Drain Current (t = 300 μs)		I _{DM}	- 1.5	A	
Continuous Source-Drain Diode Current	T _A = 25 °C	۱ _S	- 0.16 ^{b, c}		
Maximum Bower Dissinction	T _A = 25 °C	P _D	0.19 ^{b, c}	w	
Maximum Power Dissipation	T _A = 70 °C		0.12 ^{b, c}	VV	
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marian harding to Anthian ta b	t ≤ 5 s	R _{thJA}	440	530	°C/W	
Maximum Junction-to-Ambient ^{a, b}	Steady State		540	650	C/VV	

Notes:

a. Maximum under steady state conditions is 650 °C/W.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

1

RoHS

COMPLIANT HALOGEN

FREE

Si1011X

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			·		· · · · · · · · · · · · · · · · · · ·		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = -250 \ \mu A$	- 12			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 7		m\//º	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	iD = - 230 μA		1.7		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	- 0.35		- 0.8	V	
Cata Source Laskage		$V_{DS} = 0 V, V_{GS} = \pm 5 V$			± 10		
Gate-Source Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 4.5 V			± 1	μA	
Zero Gate Voltage Drain Current	1	$V_{DS} = -12 V, V_{GS} = 0 V$			- 1	μΑ	
Zero Gale voltage Drain Current	IDSS	V_{DS} = - 12 V, V_{GS} = 0 V, T_{J} = 85 °C			- 10		
On-State Drain Current ^a	I _{D(on)}	V_{DS} \leq - 5 V, V_{GS} = - 4.5 V	- 1.5			А	
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -0.4 \text{ A}$		0.530	0.640		
		V_{GS} = - 2.5 V, I _D = - 0.2 A		0.730	0.880	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 1.8 V, I _D = - 0.1 A		0.920	1.200		
		V _{GS} = - 1.5 V, I _D = - 0.05 A		1.100	1.443		
		V _{GS} = - 1.2 V, I _D = - 0.05 A		1.650	2.475		
Forward Transconductance	9 _{fs}	V _{DS} = - 6 V, I _D = - 0.4 A		1		S	
Dynamic ^b							
Input Capacitance	C _{iss}			62		pF	
Output Capacitance	C _{oss}	V_{DS} = - 6 V, V_{GS} = 0 V, f = 1 MHz		26			
Reverse Transfer Capacitance	C _{rss}			20			
Total Gate Charge	Qg	V_{DS} = - 6 V, V_{GS} = - 4.5 V, I_D = - 0.4 A		2	4	nC	
Total Gale Charge	۵g			1.15	2		
Gate-Source Charge	Q _{gs}	V_{DS} = - 6 V, V_{GS} = - 2.5 V, I_D = - 0.4 A		0.37			
Gate-Drain Charge	Q _{gd}			0.43			
Gate Resistance	R _g	f = 1 MHz		12		Ω	
Turn-On Delay Time	t _{d(on)}			4	8		
Rise Time	t _r	V_{DD} = - 6 V, R_L = 20 Ω		11	20	- ns	
Turn-Off DelayTime	t _{d(off)}	$I_{D}\cong$ - 0.3 A, V_{GEN} = - 5 V, R_{g} = 1 Ω		9	18		
Fall Time	t _f			9	18		
Drain-Source Body Diode Characteris	tics		I				
Pulse Diode Forward Current ^a	I _{SM}				- 1.5	Α	
Body Diode Voltage	V _{SD}	I _S = - 0.3 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			12	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 0.3 A, dl/dt = 100 A/μs		5	10	nC	
Reverse Recovery Fall Time	t _a	$F = -0.0 A$, $u/ut = 100 A/\mu_0$		7		20	
Reverse Recovery Rise Time	t _b			5		ns	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

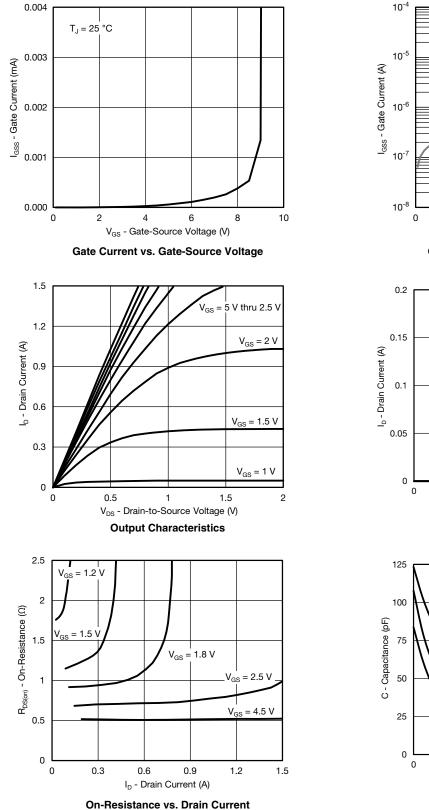
b. Guaranteed by design, not subject to production testing.

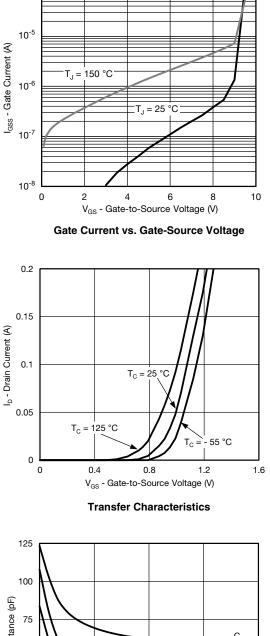
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

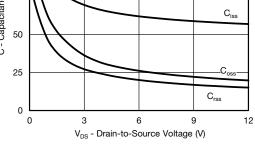
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P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







Capacitance

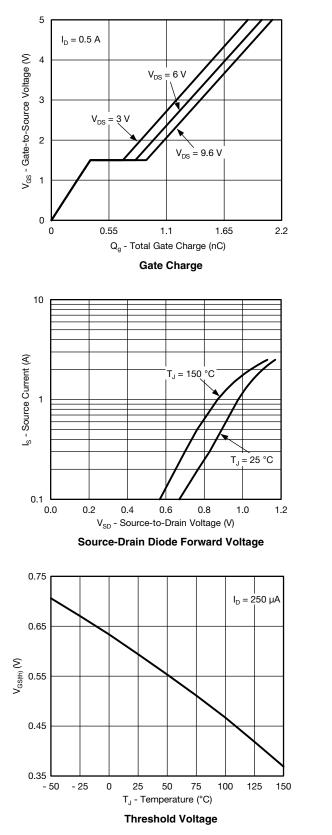
For technical questions, contact: pmostechsupport@vishay.com

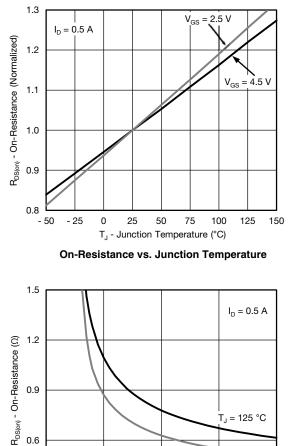
Si1011X

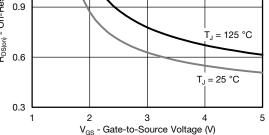


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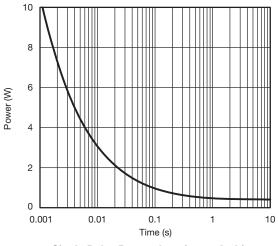
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







On-Resistance vs. Gate-to-Source Voltage

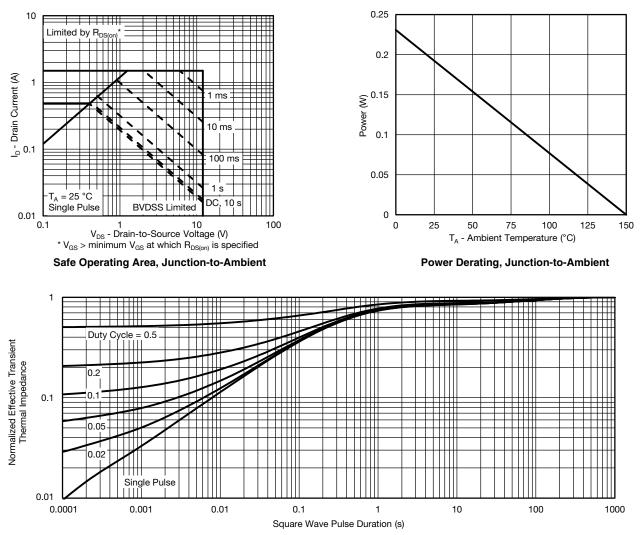


Single Pulse Power, Junction-to-Ambient

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Document Number: 62660 S12-2732-Rev. B, 12-Nov-12

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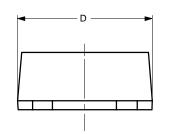
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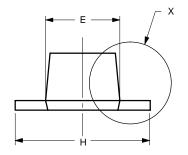
Normalized Thermal Transient Impedance, Junction-to-Ambient

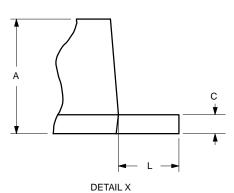
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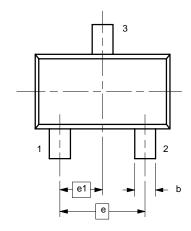


SC89-3









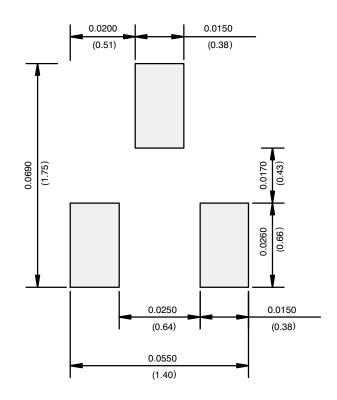
	MILLIN	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	0.60	0.80	0.024	0.031	
b	0.23	0.33	0.009	0.013	
С	0.10	0.20	0.004	0.008	
D	1.50	1.70	0.059	0.067	
E	0.75	0.95	0.030	0.037	
е	1.00	BSC	0.040 BSC		
e ₁	0.50 BSC		0.020	BSC	
н	1.50	1.70	0.059	0.067	
L	0.30	0.50	0.012	0.020	
ECN: S-03946—Rev. B, 09-Jul-01 DWG: 5869					

Application Note 826

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RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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